

Please add new claim 19 as follows:

--19 A flexible wiring board comprising:  
a first metal film;  
a second metal film;  
at least one bump between the first and second metal films to electrically connect the first and second metal films; and  
means for pressing the at least one bump against at least one of the first and second metal films by shrinking when heat is applied to the flexible wiring board.--

REMARKS

Claims 14-19 are pending. By this Amendment, claim 14 is amended and new claim 19 is added. No new matter has been added. Reconsideration of the application in view of the amendments and the following remarks is respectfully requested.

The attached Appendix includes a marked-up copy of the rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Applicants appreciate the courtesies extended to Applicants' representative during the April 18 personal interview with Examiner Patel and Primary Examiner Cuneo and during the April 24 telephonic interview with Examiner Patel. The points discussed are incorporated into the following remarks.

Claims 14-18 stand rejected under 35 U.S.C. §103(a) over Odaira (U.S. Patent No. 5,600,103) in view of Schmidt (U.S. Patent No. 5,457,881). Applicants respectfully traverse the rejection.

In particular, neither Odaira nor Schmidt, individually or in combination, disclose or suggest a flexible wiring board in which at least adjacent two patterned metal films are electrically connected to each other via bumps, a resin film includes a solvent, and the resin film is thermally shrinkable to press the bumps against the at least adjacent two patterned